

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJU60SN08
Package Type :	TO-252-2L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.88%
Lead Frame	Iron	7439-89-6	0.1000%	57.93%
	Phosphorus	7723-14-0	0.2125%	
	Copper	7440-50-8	99.6834%	
	Nickel (Ni)	7440-02-0	0.0041%	
Soft Solder	Lead	7439-92- 1	92.50%	1.11%
	Tin	7440-31-5	5.00%	
	Silver	7440-22-4	2.50%	
Wire	Al	7429-90-5	99.9960%	0.31%
	Ni	7440-02-0	0.0008%	
	Si	7440-21-3	0.0008%	
	Fe	7439-89-6	0.0008%	
	Mg	7439-95-4	0.0003%	
	Cu	7440-50-8	0.0007%	
	Other	Trade secret	0.0006%	
Mold Compound	Epoxy Resin A	Trade Secret	75.50%	38.48%
	Epoxy resin B	Trade Secret	13.00%	
	Phenol Resin	Trade Secret	8.00%	
	Silica(Amorphous) A	60676-86-0	3.00%	
	Silica(Amorphous) B	7631-86-9	0.50%	
	Carbon black	1333-86-4	99.99%	
Plating	Tin	7440-31-5	0.01%	1.28%
	Other	/	0.1000%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.